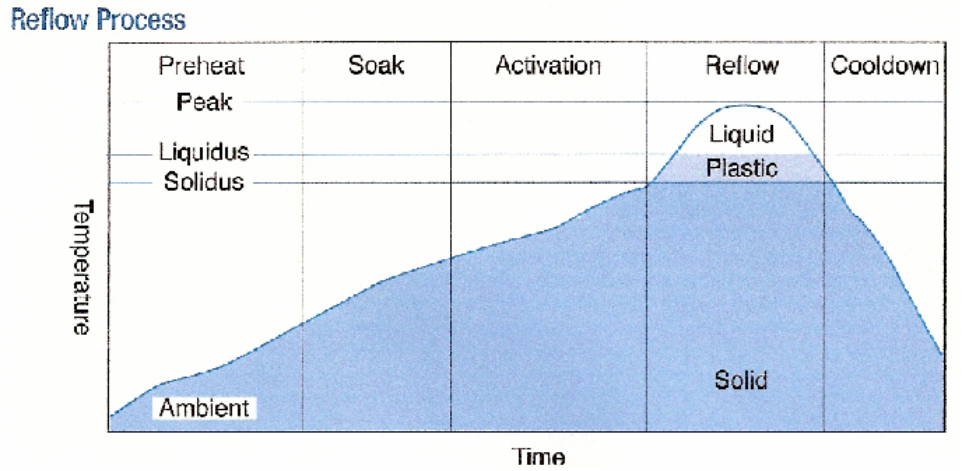

Max temp / Times	
220 C	90 Sec
230 C	60 Sec
245 C	30 Sec
260 C	15 Sec

ComNav Engineering recommends EFD SN96.5, Ag3.0, Cu 0.5 Solder for attachment. This alloy is Solidus @ 217 deg C and Liquidus @ 219 deg C

Pre-Heat:

Duration: 45 to 90 seconds During PreHeat ramp up to 110 deg C @ ½ to 2 deg per second

Soak:

Duration: 20 to 90 seconds Used to stabilize temperature across entire product. Ramp temperature from 110 deg C to 140 deg C @ ½ to 3 deg per second

Activation:

Duration: 10 to 90 seconds Allows the flux to activate and clean the surface to be soldered. Ramp temperature from 140 deg C to 217 deg C @ ½ to 3 deg per second.

Reflow:

Duration: 25 to 90 seconds Allows the solder to reflow. Control peak temperature to between 20-25 deg C above liquidus temperature. Ramp temperature from 217 deg C to 244 deg C (MAX) @ 1 to 3 deg per second.

Cool down:

Duration: 60 to 90 seconds Allows the solder to solidify. Do not cool too fast or solder joint could crack. Ramp temperature from 244 deg C (MAX) to 40-60 deg C @ 2 to 3 deg per second.

Paraphrased from EFD Reflow Profiling Guide